8-Bit Bus Front-Loading Latch Transceivers — Advanced CMOS-TTL Compatible

74ACT646 74ACT648

Features/Benefits

- **Bidirectional bus transceiver and register**
- **Independent registers for A and B buses**
- **Real-time data transfer or stored data transfer**
- **24-pin SKINNYDIP® saves space**
- **Three-state outputs drive bus lines**
- **Low quiescent supply current of <10 μA (typical)**
- **Active supply current at about 20% LS equivalent**
- **Wide commercial operating supply and temperature ranges 4.5 V to 5.5 V; −40°C to +85°C**

Ordering Information

PART NUMBER	PKG	TEMP	POLARITY	OUTPUT	TECH
74ACT646	NS,JS	Com	Noninvert	Three-state	CMOS
74ACT648	NS,JS	Com	Invert		

Description

This 8-bit bus transceiver with three-state outputs has sixteen D-type flip-flops and multiplexers. The bus-oriented pinout of the part is shown in the Pin Configuration. The internal gate-level hardware configurations for the 'ACT646/648 are given in the Logic Diagram. The basic repeated element, consisting of an edge-triggered flip-flop paralleled with a bypassing path, or "feed-through", into a two-way multiplexer is sometimes called a "front-loading latch."

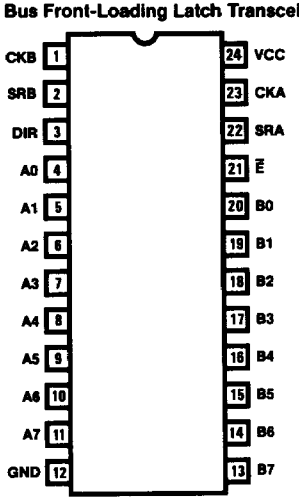
A pair of multiplexers are used to distribute two bytes of data through the part. The data-routing combinations offered by the multiplexers provide flexibility in directing data to or from either bus, and/or either register. Data is loaded into registers A or B upon the rising edge of the appropriate clock signals. CKA clocks register A, which receives data from the B bus directly at its inputs. Similarly, CKB clocks register B, which has the A bus available directly at its inputs. Control of the multiplexers is provided by two select lines (one per register), SRA and SRB. Command of the outputs is performed by enable line $\overline{E}$, and direction line DIR.

When $\overline{E}$ is High, data from the buses can be stored into register A and B. When $\overline{E}$ is Low and DIR is High, the direction of operation is from A to B, when $\overline{E}$ and DIR are Low, the direction of operation is from B to A.

SRA is used to select between register A and the B bus, and then to route the data to a controlled buffer connected to the A bus. Likewise, SRB selects between register B and the A bus, and then routes the data to the B bus through a controlled buffer.

Pin Configurations

'ACT646/648
8-Bit Bus Front-Loading Latch Transceiver



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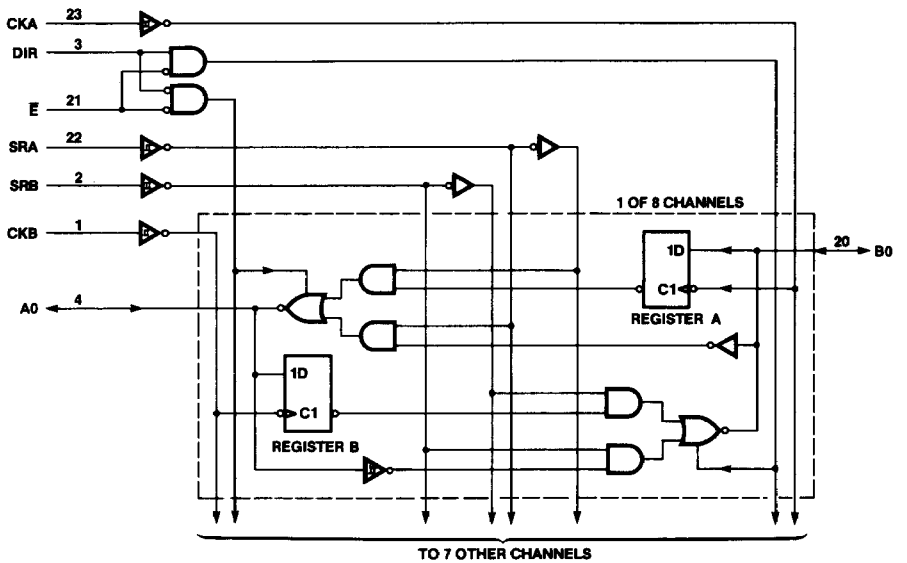
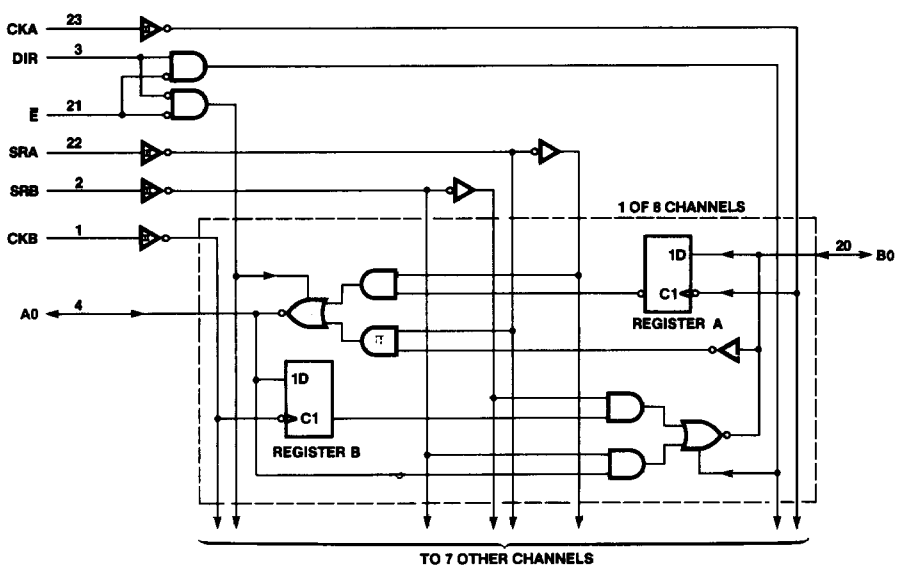
2175 Mission College Blvd. Santa Clara, CA 95054-1592 Tel: (408) 970-9700 TWX: 910-338-2374
TWX: 910-338-2376
Monolithic Memories MMI

Logic Diagrams

'ACT646 (Non-Inverting)



'ACT648 (Inverting)



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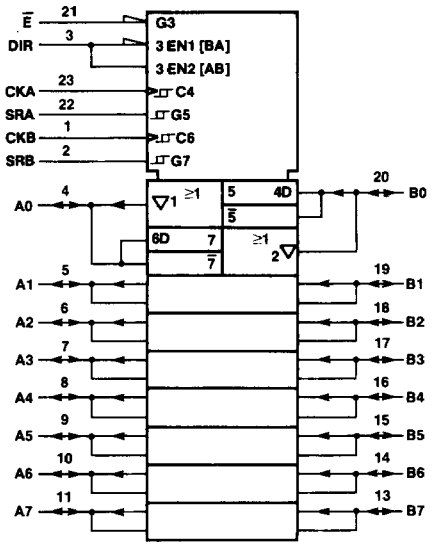
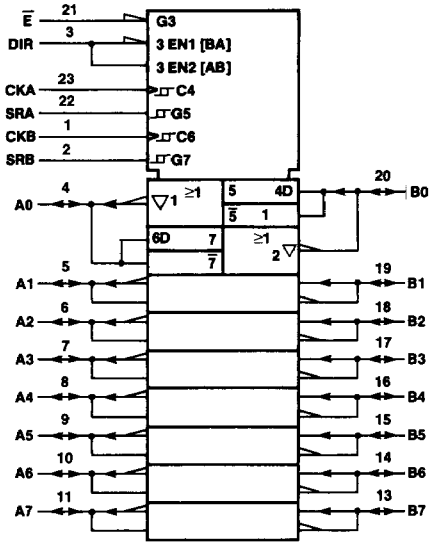
IEEE Symbols

'ACT646

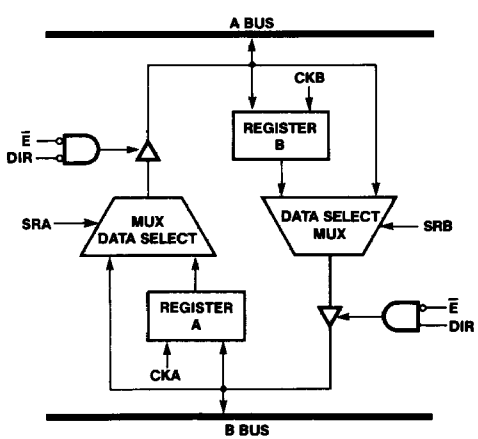


'ACT648

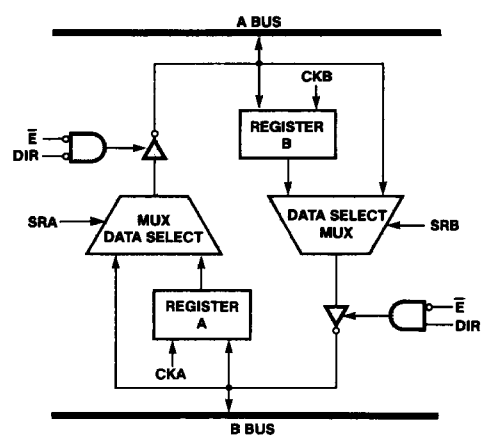


Block Diagrams

'ACT646 (Non-Inverting)



'ACT648 (Inverting)



Function Table
Nomenclature Description

$\overline{E}$: To enable A-to-B or B-to-A operation.

DIR: To select the direction of operation.

$\overline{E}$	DIR	OPERATION DIRECTION
L	L	B-to-A
L	H	A-to-B
H	X	A and B buses both are inputs (Storage)

SRA/SRB: To select the output data coming from the A/B register if SRA/SRB is a High level; otherwise, directly from the input data bus.

A0-A7: Eight input/output pins on the A side.

B0-B7: Eight input/output pins on the B side.

CKA/CKB: Clock for Register A/B.

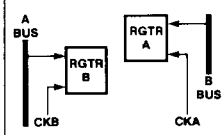
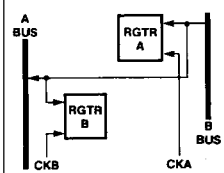
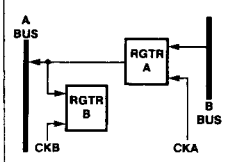
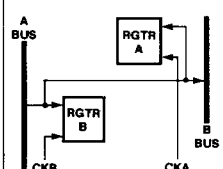
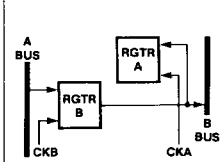
X: H or L state irrelevant ("Don't Care" condition).

↑: Positive edge of clock causes clocking, if clock enable is asserted.

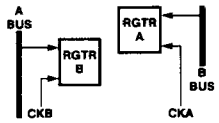
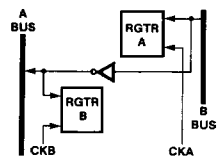
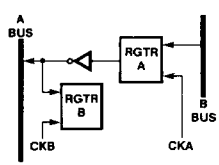
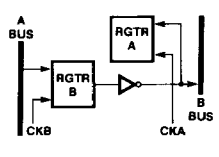
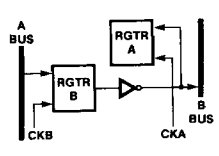
UC: H or L or ↓ case (nonclocked operation).

RGTR: Register.

Bus Operation for 'ACT646

OPERATION	CONTROL				DATA I/O		BLOCK DIAGRAM	CLOCK ENABLE		'ACT646
	$\overline{E}$	DIR	SRA	SRB	A0-A7	B0-B7		CKA	CKB	
Storage	H	X	X	X	Input	Input		UC	UC	No operation
								UC	↑	Real time A bus data → RGTR B
								↑	UC	Real time B bus data → RGTR A
								↑	↑	Real time A bus data → RGTR B Real time B bus data → RGTR A
Real time B-to-A Operation	L	L	L	X	Output	Input		UC	UC	Real time B bus data → A bus
								UC	↑	Real time B bus data → A bus Real time B bus data → RGTR B
								↑	UC	Real time B bus data → A bus Real time B bus data → RGTR A
								↑	↑	Real time B bus data → A bus Real time B bus data → RGTR A Real time B bus data → RGTR B
Stored data B-to-A Operation	L	L	H	X	Output	Input		UC	UC	RGTR A data → A bus
								UC	↑	RGTR A data → A bus RGTR A data → RGTR B
								↑	UC	Real time B bus data → RGTR A RGTR A data → A bus
								↑	↑	Real time B bus data → RGTR A RGTR A data → A bus RGTR A data → RGTR B
Real time A-to-B Operation	L	H	X	L	Input	Output		UC	UC	Real time A bus data → B bus
								UC	↑	Real time A bus data → B bus Real time A bus data → RGTR B
								↑	UC	Real time A bus data → B bus Real time A bus data → RGTR A
								↑	↑	Real time A bus data → B bus Real time A bus data → RGTR A Real time A bus data → RGTR B
Stored data A-to-B Operation	L	H	X	H	Input	Output		UC	UC	RGTR B data → B bus
								UC	↑	Real time A bus data → RGTR B RGTR B data → B bus
								↑	UC	RGTR B data → B bus RGTR B data → RGTR A
								↑	↑	Real time A bus data → RGTR B RGTR B data → B bus RGTR B data → RGTR A

Bus Operation for 'ACT648

OPERATION	CONTROL				DATA I/O		BLOCK DIAGRAM	CLOCK ENABLE		'ACT648
	$\overline{E}$	DIR	SRA	SRB	A0-A7	B0-B7		CKA	CKB	
Storage	H	X	X	X	Input	Input		UC	UC	No operation
								UC	↑	Real time A bus data → RGTR B
								↑	UC	Real time B bus data → RGTR A
								↑	↑	Real time A bus data → RGTR B Real time B bus data → RGTR A
Real time B-to-A Operation	L	L	L	X	Output	Input		UC	UC	Real time $\overline{B}$ bus data → A bus
								UC	↑	Real time $\overline{B}$ bus data → A bus Real time $\overline{B}$ bus data → RGTR B
								↑	UC	Real time $\overline{B}$ bus data → A bus Real time B bus data → RGTR A
								↑	↑	Real time $\overline{B}$ bus data → A bus Real time B bus data → RGTR A Real time $\overline{B}$ bus data → RGTR B
Stored data B-to-A Operation	L	L	H	X	Output	Input		UC	UC	RGTR $\overline{A}$ data → A bus
								UC	↑	RGTR $\overline{A}$ data → A bus RGTR $\overline{A}$ data → RGTR B
								↑	UC	Real time B bus data → RGTR A RGTR $\overline{A}$ data → A bus
								↑	↑	Real time B bus data → RGTR A RGTR $\overline{A}$ data → A bus RGTR $\overline{A}$ data → RGTR B
Real time A-to-B Operation	L	H	X	L	Input	Output		UC	UC	Real time $\overline{A}$ bus data → B bus
								UC	↑	Real time $\overline{A}$ bus data → B bus Real time A bus data → RGTR B
								↑	UC	Real time $\overline{A}$ bus data → B bus Real time $\overline{A}$ bus data → RGTR A
								↑	↑	Real time $\overline{A}$ bus data → B bus Real time $\overline{A}$ bus data → RGTR A Real time A bus data → RGTR B
Stored data A-to-B Operation	L	H	X	H	Input	Output		UC	UC	RGTR $\overline{B}$ data → B bus
								UC	↑	Real time A bus data → RGTR B RGTR $\overline{B}$ data → B bus
								↑	UC	RGTR $\overline{B}$ data → B bus RGTR $\overline{B}$ data → RGTR A
								↑	↑	Real time A bus data → RGTR B RGTR $\overline{B}$ data → B bus RGTR $\overline{B}$ data → RGTR A

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Absolute Maximum Ratings

Supply voltage, V_{CC} ..... −0.5 V to 7.0 V
DC input voltage, V_I ..... −0.5 V to V_{CC} +0.5 V
DC output voltage, V_O ..... −0.5 V to V_{CC}+0.5 V
DC output source/sink current per output pin, I_O ..... ±35 mA
DC V_{CC} or ground current, I_{CC} or I_{GND} ..... ±100 mA
Input diode current, I_{IK}:
V_I <0 ..... −20 mA
V_I >V_{CC} ..... +20 mA
Output diode current, I_{OK}:
V_O <0 ..... −20 mA
V_O >V_{CC} ..... +20 mA
Storage temperature ..... −65 to +150°C

Operating Conditions

SYMBOL	PARAMETER		COMMERCIAL MIN	TYP	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
T_A	Operating free-air temperature		−40		85	°C
t_w	Width of clock	High	20			ns
		Low	20			
t_{su}	Set up time		25↑			ns
t_h	Hold time		0↑			ns
t_r	Input rise time at V_I = 4.5 V		0		500	ns
t_f	Input fall time at V_I = 4.5 V		0		500	ns
I_{OH}	High-level output current				−6	mA
I_{OL}	Low-level output current				12	mA

↑ The arrow indicates the Low-to-High transition of the clock input used as reference.

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS		25°C MIN TYP MAX	COMMERCIAL MIN TYP MAX	UNIT
V_{IL}	Low-level input voltage			0.8	0.8	V
V_{IH}	High-level input voltage			2	2	V
I_{IN}	Input current	V_{CC} = MAX	V_I = V_{CC} or GND	±1.0	±1.0	μA
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IL} = MAX, V_{IH} = MIN	I_{OL} = 20 μA	0.1	0.1	V
			I_O = 6 mA	0.32	0.37	
			I_{OL} = 12 mA	0.4	0.4	
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IL} = MAX, V_{IH} = MIN	I_{OH} = -20 μA	3.4	3.4	V
			I_{OH} = -6 mA	2.4	2.4	
I_{OZ}	Off-state output current	V_{CC} = MAX	V_O = V_{CC} or GND	±10	±30	μA
I_{CC}*	Quiescent supply current	V_{CC} = MAX	V_I = V_{CC} or GND	10	40	μA

* See I_{CC} vs. Frequency chart.

Switching Characteristics

SYMBOL	PARAMETER	TEST CONDITIONS (See Test Load/Waveform)	COMMERCIAL T_A = 25°C MIN	MAX	COMMERCIAL MIN	MAX	UNIT
t_{PLH}	Data to output delay	C_L = 50 pF		38		45	ns
t_{PHL}				38		45	
t_{PLH}	Clock to output delay			32		38	ns
t_{PHL}				32		38	
t_{PLH}	Select to output delay* (data input high)			32		35	ns
t_{PHL}				32		35	
t_{PLH}	Select to output delay* (data input low)			32		35	ns
t_{PHL}				32		35	
t_{PZL}	Output enable delay	R_L = 1KΩ, C_L = 50 pF		40		45	ns
t_{PZH}				40		45	
t_{PLZ}	Output disable delay			35		40	ns
t_{PHZ}				35		40	
t_{PZL}	Direction enable delay			40		45	ns
t_{PZH}				35		40	
t_{PLZ}	Direction disable delay			30		35	ns
t_{PHZ}				30		35	

* See Figure 4.

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Test Waveforms

Setup Time/Hold Time

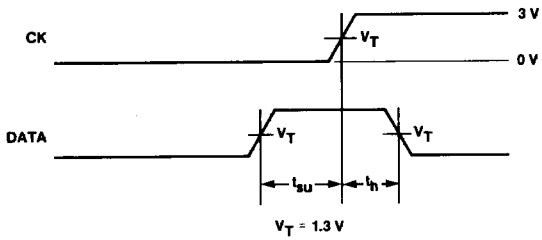


Figure 1.

Bus Data To Bus Output Delay

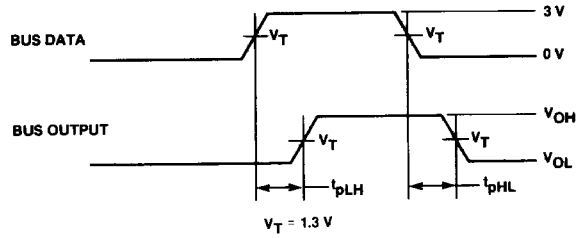


Figure 2.

CK To Bus Output Propagation Delay Time

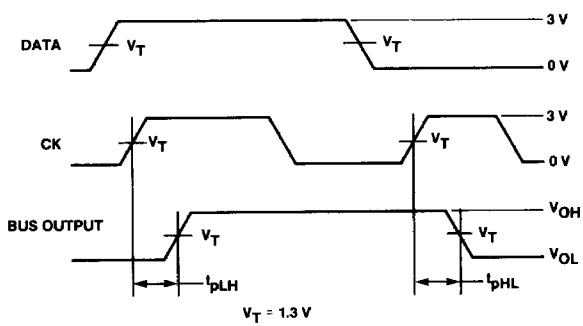
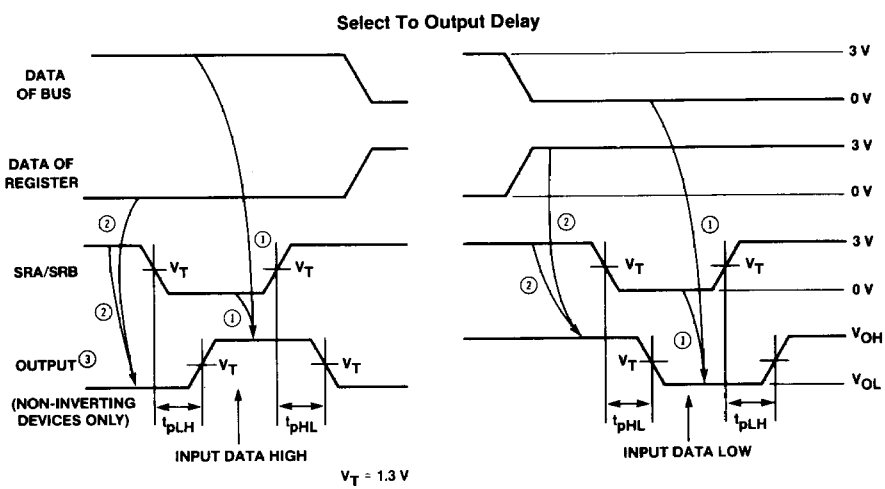


Figure 3.

Select To Output Delay



NOTES: 1. When SRA/SRB is low, the input data will transfer to output bus.
2. When SRA/SRB is high, the data of register will transfer to output bus.
3. For the inverting devices, the timing is similar, but the output is opposite to that for the non-inverting devices.

Figure 4.

Enable/Disable/Direction-Change Delay

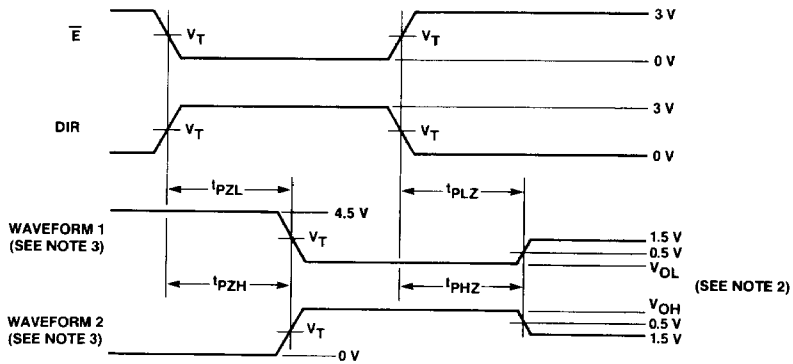


Figure 5.

Test Load

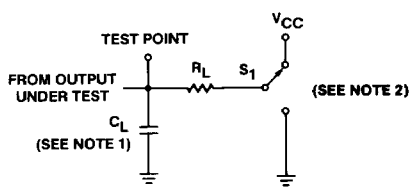


Figure 6.

NOTES 1. C_L includes probe and jig capacitance.

2. When measuring t_{PLZ} and t_{PZL}, S_1 is tied to V_{CC}. When measuring t_{PHZ} and t_{PZH}, S_1 is tied to ground.

   When measuring propagation delay times of three-state outputs, S_1 is open, i.e., not connected to V_{CC} or ground.

3. Waveform 1 is for an output with internal conditions such that the output is Low except when disabled by the output control.

   Waveform 2 is for an output with internal conditions such that the output is High except when disabled by the output control.

4. In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily.

5. All input pulses are supplied by generators having the following characteristics: PRR ≤1 MHz, t_r ≤6 ns, t_f ≤6 ns, Z_{out} = 50 Ω.

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Typical ICC vs. Frequency